

## PRESS RELEASE

### A trip around the world with DELO-adhesive

Besides electronic chips of the semi-conductor manufacturers Philips and Infineon Technologies AG, the new electronic passports, which will be officially introduced in Germany in November 2005, will also contain adhesive of the company DELO Industrial Adhesives. The chips providing the respective biometric data, such as particulars and digital facial images, are directly bonded onto the chip housing by means of a so-called Die Attach adhesive developed by DELO. Afterwards, the chip is electronically contacted by wires. In passport controls, these data can be transferred to the reader unit without contact by an antenna which is interconnected with the chip.

Besides a closer correlation between person and passport, maximum fraud resistance, which nearly eliminates unauthorized utilization of personal data, is achieved with this new electronic passport.

As a leading manufacturer in the field of industrial adhesives, DELO is especially distinguished by its innovations in the smart card technology. Throughout the world, there is a smidge of DELO adhesive in three of four chip cards, such as phone cards or bank cards.

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